

## Appendix 2

Clean copy of the amended claims.

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1. An optical write head comprising a substrate, and a plurality of light-emitting device array chips arranged on the substrate in a straight line or in a staggered layout so as to oppose a rod lens array, each of the light-emitting array device chips having a light-emitting device array, wherein the rod lens array, a substrate support member for supporting the substrate, and a driver circuit board are each secured directly to a support member.

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3. The optical write head according to claim 1, wherein at least one frame of the rod lens array to be bonded to said support member is a glass plate.

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5. The optical write head according to claim 1, wherein at least one slit of V-shaped cross section for injecting an adhesive is formed in a portion of a surface of the support member to be brought into contact with the rod lens array, so as to extend in the longitudinal direction of the rod lens array, and a plurality of adhesive injection holes are formed in the at least one slit so as to penetrate through the support member to a reverse side thereof.

6. The optical write head according to claim 1, wherein at least two positioning pins are provided at predetermined positions on the substrate support member.

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8. A method of assembling an optical write head comprising a substrate, and a plurality of light-emitting device array chips arranged on the substrate in a straight line or in a staggered layout so as to oppose a rod lens array, each of the light-emitting array device chips having a light-emitting device array, wherein the rod lens array, a substrate support member for supporting the substrate, and a driver circuit board are each secured directly to a support member, wherein at least two rotatable eccentric pins penetrating through the support member are provided so as to come into contact with the substrate support member, comprising the step of rotating the at least two eccentric pins to thereby move the substrate

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support member kept in contact with the eccentric pins and adjust the distance between a light-emission section of the light-emitting device array and a light-incident end face of the rod lens array.

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9. A method of assembling an optical write head comprising a substrate, and a plurality of light-emitting device array chips arranged on the substrate in a straight line or in a staggered layout so as to oppose a rod lens array, each of the light-emitting array device chips having a light-emitting device array, wherein the rod lens array, a substrate support member for supporting the substrate, and a driver circuit board are each secured directly to a support member, comprising the step of die-bonding the light-emitting device array chips to a predetermined location on the substrate support member while being positioned with respect to a reference plane of the substrate support member.

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10. An optical write head comprising a substrate, and a plurality of light-emitting device array chips arranged on the substrate in a straight line or in a staggered layout so as to oppose a rod lens array, each of the light-emitting device array chips having a light-emitting device array, wherein the light-emitting device array chips are mounted directly on a flexible printed circuit sheet.

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11. The optical write head according to claim 10, wherein a reverse surface of a light-emitting device array chip mount section of the flexible printed circuit sheet is disposed in close contact with a member having rigidity.

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15. The optical write head according to claim 11, wherein reference position marks for specifying respective positions at which the light-emitting array chips are to be arranged are provided on a surface of the member which has rigidity and are disposed in close contact with the flexible printed circuit sheet.

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30. The optical write head according to claim 18, wherein a frame of the rod lens array is formed from glass, and the metallic member is nickel alloy or titanium.

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31. The optical write head according to claim 18, wherein the light-emitting

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device array is a self-scan-type light-emitting device array.

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